

Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32674 ... B32678

Date: May 2009

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MKP DC link - high power series

Typical applications

For high ripple current modules in:

- Frequency converters
- Industrial and high-end power supplies
- Solar inverters

Climatic

- Max. operating temperature: 105 °C (case)
- Climatic category (IEC 60068-1): 40/100/56

Construction

- Dielectric: metallized polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Excellent self-healing properties
- Over-voltage capability
- Optimized electrical contact
- High frequency ripple current
- High reliability
- Long useful life

Terminals

- Parallel wire leads, lead-free tinned
- 2-pin and 4-pin versions
- Standard lead lengths: 6 -1 mm
- Special lead lengths are available on request

Marking

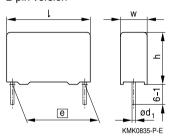
Manufacturer's logo and lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated DC voltage

Delivery mode

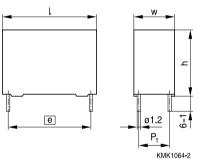
Bulk (untaped, lead length 6-1 mm)

Dimensional drawings

2-pin version



4-pin version



Dimensions in mm

Version	Lead spacing	Lead diameter d ₁	Туре
2-pin	27.5	0.8	B32674D
4-pin	37.5	1.2	B32676G
4-pin	52.5	1.2	B32678G



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Overview of available types

Lead spacing	27.5	mm				37.5	mm				52.5	mm			
Туре	B326					B326					B32678				
Page	4					6				8					
V _R (V DC)	300	450	630	750	875	300	450	630	750	875	300	450	630	750	875
C _R (μF)															
0.47															
0.68															
1.0															
1.5															
2.2															
3.0															
3.3															
4.0															
4.7															
5.0															
5.6															
6.0															
6.8															
7.5															
8.0															
8.2															
9.0															
10															
12															
14															
15															
20															
22															
25															
30															
35															
40															
47															
60															





B32674

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Ordering codes and packing units (lead spacing 27.5 mm)

C _R	Max. dimensions	P ₁	Ordering code	I _{RMS,max}	I _{RMS,max}	ESR _{typ}	Untaped
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm		Α	Α	mΩ	pcs./MOQ
V _{R,85} ° _C =	: 300 V DC, V _{op,70 °C} =	450	V DC				
2.2	$11.0 \times 19.0 \times 31.5$	_	B32674D3225+000	7.5	6.5	7.5	1280
3.3	$12.5 \times 21.5 \times 31.5$	_	B32674D3335+000	9.0	8.0	5.3	1120
4.7	$14.0\times24.5\times31.5$	_	B32674D3475+000	11.0	9.5	4.1	1040
5.0	$15.0 \times 24.5 \times 31.5$	_	B32674D3505+000	11.0	10.0	4.0	960
5.6	$15.0\times24.5\times31.5$	_	B32674D3565+000	11.5	10.5	3.9	960
6.8	$18.0\times27.5\times31.5$	_	B32674D3685+000	12.5	11.5	3.7	800
8.0	$16.0 \times 32.0 \times 31.5$	_	B32674D3805+000	13.5	12.5	3.4	880
8.2	$18.0\times33.0\times31.5$	_	B32674D3825+000	14.0	13.0	3.2	800
10	$21.0 \times 31.0 \times 31.5$	_	B32674D3106+000	15.0	14.0	2.9	720
12	$21.0\times31.0\times31.5$	_	B32674D3126+000	16.0	15.0	2.5	640
V _{R,85} ° _C =	: 450 V DC, V _{op,70 °C} =	630	V DC				
1.5	$11.0 \times 19.0 \times 31.5$	_	B32674D4155+000	6.5	6.0	9.2	1280
2.2	$12.5 \times 21.5 \times 31.5$	_	B32674D4225+000	8.0	7.0	7.8	1120
3.3	$15.0\times24.5\times31.5$	_	B32674D4335+000	9.5	8.5	5.2	960
4.7	$18.0 \times 27.5 \times 31.5$	_	B32674D4475+000	11.5	10.5	5.0	800
5.0	$16.0 \times 32.0 \times 31.5$	_	B32674D4505+000	12.0	11.0	5.0	880
5.6	$18.0\times33.0\times31.5$	_	B32674D4565+000	12.5	11.0	4.4	800
6.0	$21.0 \times 31.0 \times 31.5$	_	B32674D4605+000	13.0	11.5	4.3	720
6.8	$22.0\times36.5\times31.5$	_	B32674D4685+000	14.0	12.5	4.0	640
7.5	$22.0\times36.5\times31.5$	_	B32674D4755+000	15.0	13.0	3.9	640
V _{R,85} ° _C =	: 630 V DC, V _{op,70 °C} =	: 800	V DC				
1.0	$11.0 \times 19.0 \times 31.5$	_	B32674D6105+000	5.0	4.5	14.4	1280
1.5	$12.5 \times 21.5 \times 31.5$	_	B32674D6155+000	6.5	6.0	14.3	1120
2.2	$15.0 \times 24.5 \times 31.5$	_	B32674D6225+000	7.0	6.0	8.0	960
3.3	$16.0 \times 32.0 \times 31.5$	_	B32674D6335+000	7.0	6.0	6.5	880
4.7	$22.0 \times 36.5 \times 31.5$	_	B32674D6475+000	9.5	9.5	5.8	640
5.0	$22.0\times36.5\times31.5$	_	B32674D6505+000	10.5	9.5	5.8	640

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$



MKP DC link – high power series



B32674

Ordering codes and packing units (lead spacing 27.5 mm)

C _R	Max. dimensions	P ₁	Ordering code	I _{RMS,max}	I _{RMS,max}	ESR_{typ}	Untaped
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm		Α	Α	mΩ	pcs./MOQ
V _{R,85} ° _C =	750 V DC, V _{op,70 °C} =	900	V DC				
0.68	$11.0 \times 19.0 \times 31.5$	_	B32674D1684+000	5.0	4.5	23.3	1280
1.0	$12.5 \times 21.5 \times 31.5$	_	B32674D1105+000	6.0	5.5	12.4	1120
1.5	$14.0 \times 24.5 \times 31.5$	_	B32674D1155+000	7.5	6.0	9.5	1040
2.2	$18.0 \times 27.5 \times 31.5$	_	B32674D1225+000	9.0	7.5	6.6	800
3.3	$21.0 \times 31.0 \times 31.5$	_	B32674D1335+000	10.0	9.0	6.0	720
4.0	$22.0 \times 36.5 \times 31.5$	_	B32674D1405+000	11.0	10.0	5.6	640
V _{R,85} ° _C =	= 875 V DC, V _{op,70 °C} =	1050	V DC				
0.47	$11.0 \times 19.0 \times 31.5$	_	B32674D8474+000	5.0	4.5	22.9	1280
0.68	$11.0 \times 21.0 \times 31.5$	_	B32674D8684+000	6.0	5.5	18.6	1280
1.0	$13.5 \times 23.0 \times 31.5$	_	B32674D8105+000	7.5	6.0	13.6	1040
1.5	$18.0 \times 27.5 \times 31.5$	_	B32674D8155+000	7.0	6.5	8.5	800
2.2	$18.0 \times 33.0 \times 31.5$	_	B32674D8225+000	10.0	9.0	5.1	800
3.0	$22.0 \times 36.5 \times 31.5$	_	B32674D8305+000	11.0	10.0	6.8	640

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$





B32676

MKP DC link - high power series

Ordering codes and packing units (lead spacing 37.5 mm)

$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	C _R	Max. dimensions	P ₁	Ordering code	I _{RMS,max}	I _{RMS,max}	ESR _{typ}	Untaped	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		$w \times h \times l$		(composition see	70 °C	70 °C	70 °C		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$				below)	10 kHz	20 kHz	10 kHz		
15	μF	mm	mm	,	Α	Α	mΩ	pcs./MOQ	
20	$V_{R,85^{\circ}C} = 300 \text{ V DC}, V_{op,70^{\circ}C} = 450 \text{ V DC}$								
22	15	$20.0 \times 39.5 \times 42.0$	10.2	B32676G3156+000	15.0	14.0	3.2	640	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	20	$28.0 \times 37.0 \times 42.0$	10.2	B32676G3206+000	15.5	14.5	2.7	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	22	$28.0 \times 42.5 \times 42.0$	20.3	B32676G3226+000	16.0	15.0	2.6	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	25	$28.0 \times 42.5 \times 42.0$	20.3	B32676G3256+000	16.5	15.5	2.4	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	30	$30.0 \times 45.0 \times 42.0$	20.3	B32676G3306+000	17.0	16.0	2.3	400	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	35	$33.0 \times 48.0 \times 42.0$	20.3	B32676G3356+000	18.0	17.0	1.5	192	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V _{R,85} ° _C =	= 450 V DC, V _{op,70} ° _C =	630	V DC					
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	8.2	$20.0 \times 39.5 \times 42.0$	10.2	B32676G4825+000	11.5	10.0	8.8	640	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	10	$20.0 \times 39.5 \times 42.0$	10.2	B32676G4106+000	12.5	11.0	7.3	640	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	15	$28.0 \times 42.5 \times 42.0$	10.2	B32676G4156+000	14.0	13.0	5.0	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	20	$30.0 \times 45.0 \times 42.0$	20.3	B32676G4206K000	16.0	15.0	4.0	400	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	25	$33.0 \times 48.0 \times 42.0$	20.3	B32676G4256K000	18.0	17.0	1.5	192	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	V _{R,85} ° _C =	= 630 V DC, V _{op,70 °C} =	800	V DC					
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	6.8	$20.0\times39.5\times42.0$	10.2	B32676G6685+000	10.0	9.5	7.1	640	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	7.5	$20.0 \times 39.5 \times 42.0$	10.2	B32676G6755+000	10.0	9.5	6.7	640	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	8.2	$28.0 \times 37.0 \times 42.0$	10.2	B32676G6825+000	10.5	10.0	6.2	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	10	$28.0 \times 42.5 \times 42.0$	20.3	B32676G6106+000	11.0	10.5	5.7	440	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	12	$28.0 \times 42.5 \times 42.0$	20.3	B32676G6126+000	11.5	11.0	5.5	440	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	14	$30.0 \times 45.0 \times 42.0$	20.3	B32676G6146+000	12.0	11.5	3.6	400	
4.7 20.0 × 39.5 × 42.0 10.2 B32676G1475+000 11.0 10.0 7.8 640 5.6 20.0 × 39.5 × 42.0 10.2 B32676G1565+000 11.5 10.5 7.1 640 6.8 28.0 × 37.0 × 42.0 20.3 B32676G1685+000 12.5 11.5 6.7 440 9.0 28.0 × 42.5 × 42.0 20.3 B32676G1905+000 14.0 13.0 6.0 440 10 30.0 × 45.0 × 42.0 20.3 B32676G1106+000 15.0 14.0 5.8 400	15	$33.0 \times 48.0 \times 42.0$	20.3	B32676G6156+000	15.0	14.0	2.3	192	
5.6 20.0 × 39.5 × 42.0 10.2 B32676G1565+000 11.5 10.5 7.1 640 6.8 28.0 × 37.0 × 42.0 20.3 B32676G1685+000 12.5 11.5 6.7 440 9.0 28.0 × 42.5 × 42.0 20.3 B32676G1905+000 14.0 13.0 6.0 440 10 30.0 × 45.0 × 42.0 20.3 B32676G1106+000 15.0 14.0 5.8 400	V _{R,85} ° _C =	750 V DC, V _{op,70 °C} =	900	V DC					
6.8 28.0 × 37.0 × 42.0 20.3 B32676G1685+000 12.5 11.5 6.7 440 9.0 28.0 × 42.5 × 42.0 20.3 B32676G1905+000 14.0 13.0 6.0 440 10 30.0 × 45.0 × 42.0 20.3 B32676G1106+000 15.0 14.0 5.8 400	4.7	$20.0 \times 39.5 \times 42.0$	10.2	B32676G1475+000	11.0	10.0	7.8	640	
9.0 28.0 × 42.5 × 42.0 20.3 B32676G1905+000 14.0 13.0 6.0 440 10 30.0 × 45.0 × 42.0 20.3 B32676G1106+000 15.0 14.0 5.8 400	5.6	$20.0 \times 39.5 \times 42.0$	10.2	B32676G1565+000	11.5	10.5	7.1	640	
10 30.0 × 45.0 × 42.0 20.3 B32676G1106+000 15.0 14.0 5.8 400	6.8	$28.0 \times 37.0 \times 42.0$	20.3	B32676G1685+000	12.5	11.5	6.7	440	
	9.0	$28.0 \times 42.5 \times 42.0$	20.3	B32676G1905+000	14.0	13.0	6.0	440	
12 33.0 × 48.0 × 42.0 20.3 B32676G1126+000 19.5 19.0 2.7 192	10	$30.0 \times 45.0 \times 42.0$	20.3	B32676G1106+000	15.0	14.0	5.8	400	
	12	$33.0 \times 48.0 \times 42.0$	20.3	B32676G1126+000	19.5	19.0	2.7	192	

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

K = ±10%



MKP DC link – high power series



B32676

Ordering codes and packing units (lead spacing 37.5 mm)

C _R	Max. dimensions	P ₁	Ordering code	I _{RMS,max}	I _{RMS,max}	ESR _{typ}	Untaped				
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C					
			below)	10 kHz	20 kHz	10 kHz					
μF	mm	mm		Α	Α	mΩ	pcs./MOQ				
V _{R,85} ° _C =	$V_{R,85^{\circ}C} = 875 \text{ V DC}, V_{op,70^{\circ}C} = 1050 \text{ V DC}$										
3.3	$20.0 \times 39.5 \times 42.0$	10.2	B32676G8335+000	11.0	10.0	11.0	640				
4.0	$20.0\times39.5\times42.0$	10.2	B32676G8405+000	11.5	10.5	9.8	640				
4.7	$28.0 \times 37.0 \times 42.0$	20.3	B32676G8475+000	12.5	11.5	8.6	440				
6.8	$28.0 \times 42.5 \times 42.0$	20.3	B32676G8685+000	14.0	13.0	8.3	440				
7.5	$30.0 \times 45.0 \times 42.0$	20.3	B32676G8755+000	15.0	14.0	8.0	400				
10	$33.0 \times 48.0 \times 42.0$	20.3	B32676G8106K000	19.5	19.0	3.7	192				

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$





B32678

MKP DC link - high power series

Ordering codes and packing units (lead spacing 52.5 mm)

C _R	Max. dimensions	P ₁	Ordering code	I _{RMS,max}	I _{RMS,max}	ESR _{typ}	Untaped	
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C		
			below)	10 kHz	20 kHz	10 kHz		
μF	mm	mm		Α	Α	$m\Omega$	pcs./MOQ	
V _{R,85 °C} = 300 V DC, V _{op,70 °C} = 450 V DC								
40	$30.0\times45.0\times57.5$	20.3	B32678G3406+000	19.0	18.0	1.9	280	
47	$35.0 \times 50.0 \times 57.5$	20.3	B32678G3476+000	21.0	20.0	1.7	108	
60	$35.0\times50.0\times57.5$	20.3	B32678G3606K000	23.0	22.0	1.6	108	
V _{R,85 °C} =	= 450 V DC, V _{op,70 °C} =	630	V DC					
30	$35.0\times50.0\times57.5$	20.3	B32678G4306+000	19.5	18.5	2.1	108	
35	$35.0 \times 50.0 \times 57.5$	20.3	B32678G4356+000	21.0	20.0	1.7	108	
40	$35.0\times50.0\times57.5$	20.3	B32678G4406K000	22.0	21.0	1.5	108	
V _{R,85} ° _C =	= 630 V DC, V _{op,70 °C} =	= 800	V DC					
20	$35.0\times50.0\times57.5$	20.3	B32678G6206+000	17.5	16.5	2.9	108	
25	$35.0\times50.0\times57.5$	20.3	B32678G6256+000	20.0	19.0	2.6	108	
V _{R,85} ° _C =	750 V DC, V _{op,70 °C} =	900	V DC					
15	$30.0 \times 45.0 \times 57.5$	20.3	B32678G1156K000	20.0	19.5	3.7	280	
20	$35.0\times50.0\times57.5$	20.3	B32678G1206K000	21.0	20.0	2.6	108	
V _{R,85} ° _C =	875 V DC, V _{op,70 °C} =	1050	V DC					
15	$35.0\times50.0\times57.5$	20.3	B32678G8156K000	21.0	20.0	3.4	108	

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$



MKP DC link - high power series



Technical data

Reference standard: IEC 61071. All data given at T = 20 $^{\circ}$ C, unless otherwise specified.

Operating tempera	ture range (case)	Max. op	perating ten	nperature, T	op,max +10	5 °C
		Upper o	category ter	mperature T	max +10	0 °C
		Lower	category ter	mperature T	min -4	0 °C
ESR (at 10 kHz)	LS 27.5	< 3.0 ⋅	ESR _{typ}			
	LS 37.5	< 2.5 ·	ESR_{typ}			
	LS 52.5	< 1.5 ⋅	ESR_{typ}			
Insulation Resistan	ce R _{ins}	30 000	S			
given as time cons	tant					
$t = C_R \cdot R_{ins}$, rel. hur	midity ≤ 65%					
(minimum as-delive	ered values)					
DC test voltage bet	tween terminals (10 s)	1.5 · V _F	3			
DC test voltage ter	minal to case (10 s)	2110 V	AC, 50 Hz			_
Maximum peak cur	I _{P,max} =	$C_R - \frac{dV}{dt}$				
Damp heat test	56 days	s/40 °C/93%	6 relative hu	ımidity		
Limit values after d	amp heat test	Capacit	ance chan	ge I ∆C/C I	≤ 5%	
		Dissipa	tion factor o	change ∆ ta	n δ ≤ 1.5 ·	10 ⁻³ (at 1 kHz)
			on resistan	Ü		of minimum
				oo . Ins	as-deli	vered values
Reliability:	Failure rate λ	1 fit (≤ :	1 · 10 ⁻⁹ /h) a	t 0.5 · V _B , 4	0 °C	
, ,	Service life t _{SI}	`) h at V _R , 8			
	COLVIDO IIIO ISL			other operat	ing conditio	ns and
				r to chapter	•	
V _R (V DC)		300	450	630	750	875
Continuous operati	on voltage					
V _{op} (V DC) at 70 °C		450	630	800	900	1050
Continuous operati	on voltage					
V_{op} (V DC) at 85 °C	;	300	450	630	750	875
Maximum peak vol	tage	450	675			
V _{P,max} (V DC)	V _{P,max} (V DC)			950	1125	1300
For temperatures b	For temperatures between				· · · · · · · · · · · · · · · · · · ·	
85 °C and 100 °C	85 °C and 100 °C			g respect V	_{op} at 85 °C	





MKP DC link - high power series

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/us.

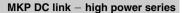
Note:

The values of dV/dt provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt values

Lead spacing	27.5	mm				37.5	37.5 mm				52.5 mm				
Туре	B326	674				B326	676				B32	678			
V _R (V DC)	300	450	630	750	875	300	450	630	750	875	300	450	630	750	875
C _R (µF)	dV/d	t in V	/µs												
0.47	_	_	_	_	150	_	_	_	_	_	_	_	_	_	_
0.68	_	_	_	125	150	_	_	_	_	_	_	_	_	_	_
1.0	_	_	100	125	150	_	_	_	_	_	_	-	_	_	_
1.5	_	75	100	125	150	_	_	_	_	_	_	_	_	_	-
2.2	40	75	100	125	150	_	_	_	_	_	_	-	_	_	_
3.0	40	_	_	_	150	_	_	_	_	_	_	_	_	_	_
3.3	40	75	100	125	_	_	_	_	_	100	_	-	_	_	_
4.0	-	ı	-	125	ı	_	-	-	I	100	1	_	ı	_	
4.7	40	75	100	_	-	_	-	_	85	100	-	-	-		_
5.0	40	75	100	_	_	_	_	_	_	_	_	-	_	_	_
5.6	40	75	_	_	_	_	_	_	85	_	_	_	_	_	_
6.0	_	75	_	_	_	_	_	_	_	_	_	_	_	_	_
6.8	-	75	-	-	ı	-	-	73	85	100	ı	_	ı	-	
7.5	-	75	_	_	_	_	_	73	_	100	_	_	_	_	_
8.0	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_
8.2	-	ı	-	-	ı	-	54	73	ı	ı	ı	_	ı	-	
9.0		-		_	-	_	-	_	85	-	-	-	-		_
10	_	_	_	_	_	_	54	73	85	100	_	_	_	_	_
12	-	ı	-	-	ı	-	-	73	85	ı	ı	_	ı	-	
14	-	_	_	_	_	_	_	73	_	_	_	_	_	_	_
15	_	_	_	_	_	22	54	73	_	_	_	_	_	60	70
20	_	_	_	_	_	22	54	_	_	_	_	_	50	60	_
22	_	_	_	_	_	22	_	_	_	_	_	-	_	-	_
25	_	_	_	_	_	22	54	_	_	_	_	_	50	_	_
30	_	_	_	_	_	22	_	_	_	_	_	35	_	_	_
35	_	_	_	_	_	22	_	_	_	_	_	35	_	_	
40	_	_	_	-	-	_	_	-	-	-	15	35		_	
47	_	-	_	-	-	_	_	-	-	-	15	_		_	_
60	_	_	_	-	_	_	_	-	-	-	15	_	_	_	



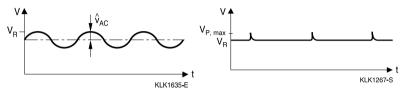




ESL values

	ESL
2-pin	25 nH
4-pin	17 nH

Typical waveforms



Restrictions:

 V_R : Maximum operating peak voltage of either polarity but of a non-reversing waveform, for which the capacitor has been designed for continuous operation.

 $\hat{\textbf{v}}_{\text{AC}}\!\leq \textbf{0.2}\,\cdot\,\textbf{V}_{\text{R}}$

 $V_{P, max}$: Maximum permissible recurrent voltage that may appear for 2% of the period.





MKP DC link - high power series

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

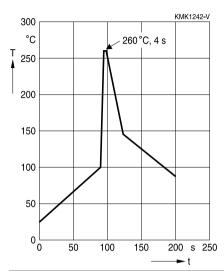
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)



MKP DC link – high power series





Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification





MKP DC link - high power series

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



MKP DC link - high power series



2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Туре	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70 °C) before they are subjected to subsequent electrical testing.

Table AManufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

Trifluoro-trichloro- ethane	Mixtures of trifluoro-trichloro-ethane with ethanol and isopropanol	Manufacturer
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil





MKP DC link - high power series

3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100 $^{\circ}$ C.

Caution:

Consult us first if you wish to embed uncoated types!



MKP DC link - high power series



Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





MKP DC link - high power series

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"



MKP DC link - high power series



Symbols and terms

Symbol	English	German	
α	Heat transfer coefficient	Wärmeübergangszahl	
$lpha_{ extsf{C}}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität	
Α	Capacitor surface area	Kondensatoroberfläche	
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität	
С	Capacitance	Kapazität	
C_R	Rated capacitance	Nennkapazität	
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung	
Δ C/C	Relative capacitance change (relative	Relative Kapazitätsänderung (relative	
	deviation of actual value)	Abweichung vom Ist-Wert)	
$\Delta C/C_R$	Capacitance tolerance (relative deviation	Kapazitätstoleranz (relative Abweichung	
	from rated capacitance)	vom Nennwert)	
dt	Time differential	Differentielle Zeit	
Δt	Time interval	Zeitintervall	
ΔT	Absolute temperature change	Absolute Temperaturänderung	
	(self-heating)	(Selbsterwärmung)	
$\Delta tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors	
ΔV	Absolute voltage change	Absolute Spannungsänderung	
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung	
	of voltage rise)	(Spannungsflankensteilheit)	
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall	
E	Activation energy for diffusion Aktivierungsenergie zur Diffusi		
ESL	Self-inductance	Eigeninduktivität	
ESR	Equivalent series resistance	Ersatz-Serienwiderstand	
f	Frequency	Frequenz	
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte	
	AC voltage due to thermal limits	Reduzierung der zulässigen	
		Wechselspannung	
f_2	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte	
	AC voltage due to current limit	Reduzierung der zulässigen	
,	December 1 for some 1	Wechselspannung	
f _r	Resonant frequency	Resonanzfrequenz	
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion	
_	Dereting factor		
F _⊤	Derating factor	Deratingfaktor	
1	Current (peak)	Stromspitze	
I _C	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)	
	current)		





MKP DC link - high power series

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
İz	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_{o}	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_i	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_{s}	Series component of dissipation factor	Serienanteil des Verlustfaktors
TA	Ambient temperature	Umgebungstemperatur
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T_{op}	Operating temperature	Beriebstemperatur
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer
V _{AC}	AC voltage	Wechselspannung





MKP DC link - high power series

Symbol	English	German
V _C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{o}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
ν̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß





MKP DC link - high power series

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

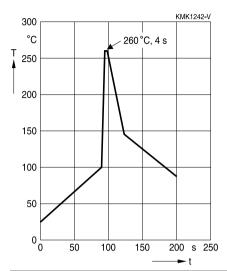
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except 2.5 \times 6.5 \times 7.2 mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)



MKP DC link – high power series





Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification





MKP DC link - high power series

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



MKP DC link - high power series



2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Туре	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70 °C) before they are subjected to subsequent electrical testing.

Table AManufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

Trifluoro-trichloro- ethane	Mixtures of trifluoro-trichloro-ethane with ethanol and isopropanol	Manufacturer
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil





MKP DC link - high power series

3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100 $^{\circ}$ C.

Caution:

Consult us first if you wish to embed uncoated types!



MKP DC link - high power series



Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	esistance to Do not exceed the tested ability to withstand	





MKP DC link - high power series

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"



MKP DC link - high power series



Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{C}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
ΔC/C	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	,
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔΤ	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)





MKP DC link - high power series

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
İz	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_{o}	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_i	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_{s}	Series component of dissipation factor	Serienanteil des Verlustfaktors
TA	Ambient temperature	Umgebungstemperatur
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
02	and voltage	-spannung
T _{op}	Operating temperature	Beriebstemperatur
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer
V _{AC}	AC voltage	Wechselspannung





MKP DC link - high power series

Symbol	English	German
V _C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{o}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
ν̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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